

L Number	Hits	Search Text	DB	Time stamp
1	2	((("5975908") or ("20020128354"))).PN.	USPAT; US-PGPUB	2004/04/16 19:01
2	2	((("5975408") or ("20020128354"))).PN.	USPAT; US-PGPUB	2004/04/16 19:12
3	0	("(chipordie)and((underfillormoldormolding)	USPATfluxor2004/04/16carboxylicor	2004/04/16 19:13
4	1103	(chip or die) and ((underfill or mold or molding) with(flux or fluxing or carboxylic or hydroxyl))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 19:16
5	1103	(chip or die) and ((underfill or mold or molding) with (flux or fluxing or carboxylic or hydroxyl))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 19:17
6	897	((chip or die) and ((underfill or mold or molding) with (flux or fluxing or carboxylic or hydroxyl))) and (@ad<20011020)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 19:17
7	76	((chip or die) and ((underfill or mold or molding) with (flux or fluxing or carboxylic or hydroxyl))) and (@ad<20011020)) and ((underfill or mold or molding) with (silica or sio or sin or (silicon adj (oxide or dioxide or nitride)) or aln or alo or (aluminum adj (oxide or nitride))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 19:19
8	1	((chip or die) and ((underfill or mold or molding) with (flux or fluxing or carboxylic or hydroxyl))) and (@ad<20011020)) and ((underfill or mold or molding) near (silica or sio or sin or (silicon adj (oxide or dioxide or nitride)) or aln or alo or (aluminum adj (oxide or nitride))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 19:19
9	38	((((chip or die) and ((underfill or mold or molding) with (flux or fluxing or carboxylic or hydroxyl))) and (@ad<20011020)) and ((underfill or mold or molding) with (silica or sio or sin or (silicon adj (oxide or dioxide or nitride)) or aln or alo or (aluminum adj (oxide or nitride)))))) and (ic or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 19:19